

from the group consisting of thermoset and thermoplastic polymers overlying said compliant layer and defining said second surface of said dielectric element.

68. A chip assembly as claimed in claim 64, wherein said compliant layer is formed from an elastomeric material.

69. A chip assembly as claimed in claim 64, wherein said compliant layer is formed from a compressible foam.

*Sub B3* 68. A chip assembly as claimed in claim 61, wherein said dielectric element includes a sheet-like, electrically conductive grounding layer disposed between said central terminals and said chip.

69. A chip assembly as claimed in claim 61, wherein some of said central terminals are disposed adjacent the edge bounding said hole.

70. A chip assembly as claimed in claim 61, wherein said plurality of central terminals are disposed at said second surface of said dielectric element. --

In the Title:

Please amend the title of the application to: -- Semiconductor Chip Package With Center Contacts. --

In the Specification:

*404b*  
*A2*

Page 1, before line 1, insert -- This is a divisional of United States Patent Application 08/861,280 filed May 21, 1997 which is in turn a continuation of United States Patent Application 08/319,966, filed on October 7, 1994, which is in turn a continuation of United States Patent Application 08/030,194, filed April 28, 1993 as the national phase of International Application PCTUS/91/06920 filed September 24, 1991. Said 030,194 Application in turn is a continuation of United States Patent Application 07/765,928, filed September 24, 1991 now United States Patent 5,347,159. Said